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The present application is related to application serial number 09/698,186 filed by K. Inoue and eleven others corresponding to Japanese Patent Application No. 11-307986 filed October 29, 1999 and Japanese Patent Application Nos. 2000-134209, 2000-134210 and 2000-134211 all of the three filed April 28, 2000, the content of which is incorporated herein by reference in its entirety, and is also related to application serial number 09/698,185 filed by K. Inoue and eleven others corresponding to Japanese Patent Application No. 11-307986 filed October 29, 1999 and Japanese Patent Application No. 2000-134214 filed April 28, 2000, the content of which is also incorporated herein by reference in its entirety.

**IN THE CLAIMS:**

Please **cancel** claims 12 and 23-34 without prejudice or disclaimer of the subject matter contained therein.

Please **add** new claims 35-50 as follows:

*electrically insulating film = inorganic or organic film.*

35. A semiconductor apparatus comprising  
13  
a semiconductor device;

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an electrically insulating layer having an inclined portion formed on the

B2 semiconductor device;  
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at least one external connection terminal formed on the electrically insulating layer; and

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a wiring formed on the electrically insulating layer and provided for electrically connecting the external connection terminal to a circuit electrode of the semiconductor device,